MEMORY смов 2 × 512 K × 16 BIT SYNCHRONOUS DYNAMIC RAM

MB811171622A-125/-100/-84/-67

CMOS 2-BANK 524,288-WORD \times 16 BIT Synchronous Dynamic Random Access Memory

DESCRIPTION

The Fujitsu MB811171622A is a CMOS Synchronous Dynamic Random Access Memory (SDRAM) containing 16,777,216 memory cells accessible in an 16-bit format. The MB811171622A features a fully synchronous operation referenced to a positive edge clock whereby all operations are synchronized at a clock input which enables high performance and simple user interface coexistence. The MB811171622A SDRAM is designed to reduce the complexity of using a standard dynamic RAM (DRAM) which requires many control signal timing constraints, and may improve data bandwidth of memory as much as 5 times more than a standard DRAM.

The MB811171622A is ideally suited for workstations, personal computers, laser printers, high resolution graphic adapters accelerators and other applications where an extremely large memory and bandwidth are required and where a simple interface is needed.

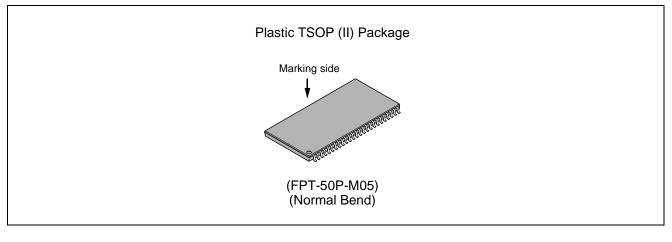
PRODUCT LINE & FEATURES

Parameter		MB8111	71622A				
Falameter	-125	-100	-84	-67			
Clock Frequency	125 MHz max.	100 MHz max.	84 MHz max.	67 MHz max.			
Burst Mode Cycle Time	8 ns min.	10 ns min.	12 ns min.	15 ns min.			
RAS Access Time	45 ns max.	54 ns max.	54 ns max. 56 ns max.				
CAS Access Time	21 ns max.	24 ns max.	26 ns max.	30 ns max.			
Access Time From Clock (CL = 3)	7.5 ns max.	8.5 ns max.	8.5 ns max.	9 ns max.			
Operating Current (Two banks active)	140 mA max.	130 mA max.	120 mA max.	110 mA max.			
Power Down Mode Current	2 mA max.						

• Single +3.3 V Supply +0.3 V tolerance

- LVTTL compatible I/O
- 2 K refresh cycles every 32.8 ms
- Dual bank operation
- Byte control by DQML/DQMU
- Burst read/write operation and burst read/ single write operation capability
- Programmable burst type, burst length, and CAS latency
- Auto-and Self-refresh (every 16 μs)
- CKE power down mode
- Output Enable and Input Data Mask

■ PACKAGE

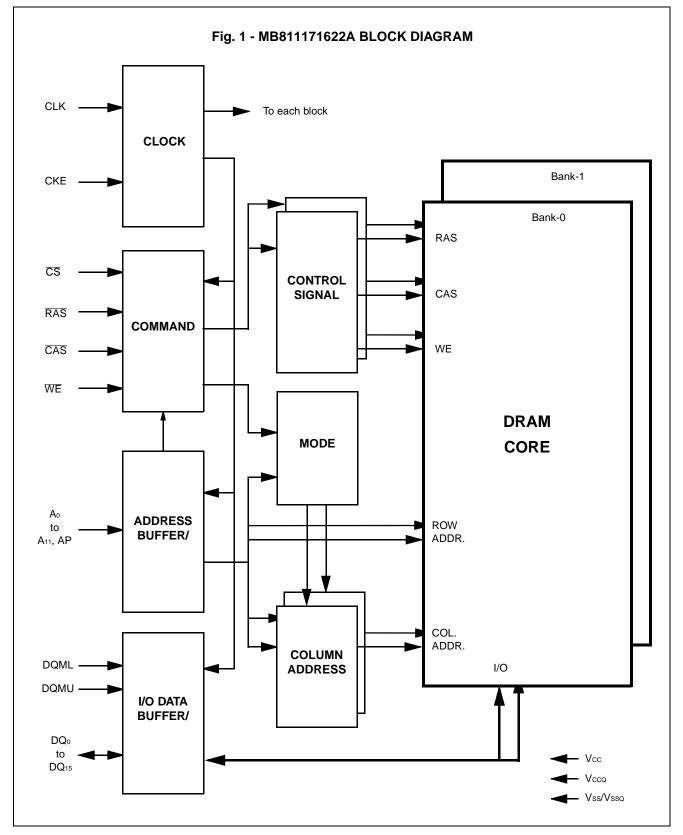


Package and Ordering Information

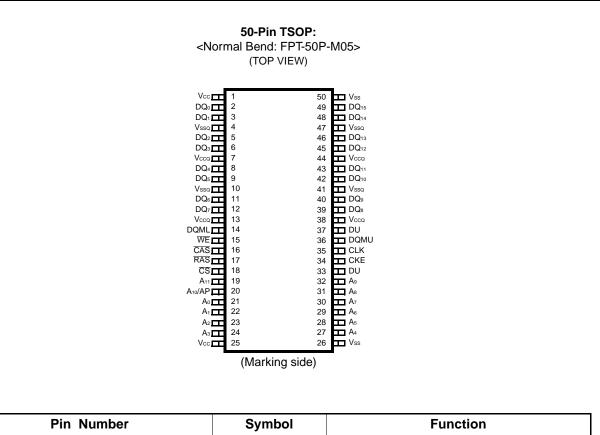
- 50-pin plastic (400 mil) TSOP-II, order as MB811171622A-xxxFN (2K Refresh)

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BLOCK DIAGRAM



■ PIN ASSIGNMENTS AND DESCRIPTIONS



Pin Number	Symbol	Function
1, 7, 13, 25, 38, 44	Vcc, Vccq	Supply Voltage
2, 3, 5, 6, 8, 9, 11, 12, 39, 40, 42, 43, 45, 46, 48, 49	DQ ₀ to DQ ₁₅	Data I/O
4, 10, 26, 41, 47, 50	Vss, Vssq *	Ground
37	DU	Don't use (leave open)
15	WE	Write Enable
16	CAS	Column Address Strobe
17	RAS	Row Address Strobe
18	CS	Chip Select
19	A11 (BA)	Bank Select
20	AP	Auto Precharge Enable
20, 21, 22, 23, 24, 27, 28, 29, 30, 31, 32	A ₀ to A ₁₀	Address Input Row: A₀ to A₁₀ Column: A₀ to A₇
33	DU	Don't use (leave open)
34	CKE	Clock Enable
35	CLK	Clock Input
14, 36	DQML, DQMU	Input Mask/Output Enable

* : These pins are connected internally in the chip.

■ FUNCTIONAL TRUTH TABLE Note 1

COMMAND TRUTH TABLE Notes 2, 3, and 4

Function	Notes	Symbol	Cł	٢E	CS	RAS	CAS	WE	A 11	A 10	۵۵.	A7-A0
ranction	Notes	Symbol	n-1	n	00	INAU	040	VVL	(BA)	(AP)	₼ 9- ₼ 0	A /- A 0
Device Deselect	*5	DESL	Н	Х	Н	Х	Х	Х	Х	Х	Х	Х
No Operation	*5	NOP	Н	Х	L	Н	Н	Н	Х	Х	Х	Х
Burst Stop		BST	Н	Х	L	Н	Н	L	Х	Х	Х	Х
Read	*6	READ	Н	Х	L	Н	L	Н	V	L	Х	V
Read with Auto-precharge	*6	READA	Н	Х	L	Н	L	Н	V	Н	Х	V
Write	*6	WRIT	Н	Х	L	Н	L	L	V	L	Х	V
Write with Auto-precharge	*6	WRITA	Н	Х	L	Н	L	L	V	Н	Х	V
Bank Active (RAS)	*7	ACTV	Н	Х	L	L	Н	Н	V	V	V	V
Precharge Single Bank		PRE	Н	Х	L	L	Н	L	V	L	Х	Х
Precharge All Banks		PALL	Н	Х	L	L	Н	L	Х	Н	Х	Х
Mode Register Set	*8, 9	MRS	Н	Х	L	L	L	L	L	L	V	V

Notes: *1. V = Valid, L = Logic Low, H = Logic High, X = either L or H.

*2. All commands assumes no CSUS command on previous rising edge of clock.

- *3. All commands are assumed to be valid state transitions.
- *4. All inputs are latched on the rising edge of clock.
- *5. NOP and DESL commands have the same effect on the part.
- *6. READ, READA, WRIT and WRITA commands should only be issued after the corresponding bank has been activated (ACTV command). Refer to STATE DIAGRAM.
- *7. ACTV command should only be issued after corresponding bank has been precharged (PRE or PALL command).
- *8. Required after power up.
- *9. MRS command should only be issued after all banks have been precharged (PRE or PALL command), and DQ is in Hi-z. Refer to STATE DIAGRAM.

DQM TRUTH TABLE

Function	Command	CI	ΚE	DQML	DQMU	
T unction	Command	n-1	n		Danio	
Data Write/Output Enable for Lower Byte	ENBL L	Н	Х	L	Х	
Data Write/Output Enable for Upper Byte	ENBL U	Н	Х	Х	L	
Data Mask/Output Disable for Lower Byte	MASK L	Н	Х	Н	Х	
Data Mask/Output Disable for Upper Byte	ENBL U	Н	Х	Х	Н	

CKE TRUTH TABLE

Current	Function No	otes	Symbol	C	٢E	CS	RAS	CAS	WE	A 11	A 10	A 9-0
State		JIES	Symbol	n-1	n	63	RA3	CAS		(BA)	(AP)	A 9-0
Bank Active	Clock Suspend Mode Entry	*1	CSUS	Н	L	Х	Х	Х	Х	Х	Х	Х
Any	Clock Suspend Continue	*1		L	L	Х	Х	Х	Х	Х	Х	Х
Clock Suspend	Clock Suspend Mode Exit			L	Н	Х	х	х	Х	х	х	х
Idle	Auto-refresh Command	*2	REF	Н	Н	L	L	L	Н	Х	Х	Х
Idle	Self-refresh Entry	*2	SELF	Н	L	L	L	L	Н	Х	Х	Х
Salf Dafrach	Self-refresh Exit		SELFX	L	Н	L	Н	Н	Н	Х	Х	Х
Self Refresh	Sell-reflesh Exit		SELFA	L	Н	Н	Х	Х	Х	Х	Х	Х
Idla	Power Down Entry		PD	Н	L	L	Н	Н	Н	Х	Х	Х
Idle	Power Down Entry		PD	Н	L	Н	Х	Х	Х	Х	Х	Х
Dracharga	Power Down Entry		PD	Н	L	L	Н	Н	Н	Х	Х	Х
Precharge	Power Down Entry		FD	Н	L	Н	Х	Х	L	Х	Х	Х
Pook Activo	Power Down Entry	*3	PD	Н	L	L	L	Н	L	V	L	Х
Back Active	Power Down Entry	3	FD	Н	L	L	L	Н	L	Х	Н	Х
Power Down	Power Down Exit			L	Н	L	Н	Н	Н	Х	Х	Х
				L	Н	Н	Х	Х	Х	Х	Х	Х

Notes: *1. The CSUS command requires that at least one bank is active. Refer to STATE DIAGRAM.

*2. REF and SELF commands should only be issued after all banks have been precharged (PRE or PALL command). Refer to STATE DIAGRAM.

*3. PD command should be issued after all banks have been precharged (PRE or PALL command). If a bank or all banks are in active state, PD command can be issued in conjuction with PRE or PALL command whichever precharge command makes all banks in idle state.

OPERATION COMMAND TABLE (Applicable to single bank)

Current State	CS	RAS	CAS	WE	Addr	Command	Function Notes
Idle	Н	Х	Х	Х	Х	DESL	NOP
	L	Н	н	Н	Х	NOP	NOP
	L	Н	н	L	Х	BST	NOP
	L	Н	L	Н	BA, CA, AP	READ/READA	Illegal *2
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Illegal *2
	L	L	н	Н	BA, RA	ACTV	Bank Active after tRCD
	L	L	н	L	BA, AP	PRE/PALL	NOP *6
	L	L	L	Н	Х	REF/SELF	Auto-refresh or Self-refresh *3
	L	L	L	L	MODE	MRS	Mode Register Set *3, 7 (Idle after I _{MRD})
Bank Active	Н	Х	Х	Х	Х	DESL	NOP
	L	Н	н	Н	Х	NOP	NOP
	L	Н	н	L	Х	BST	NOP
	L	Н	L	Н	BA, CA, AP	READ/READA	Begin Read: Determine AP
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Begin Write; Determine AP
	L	L	н	Н	BA, RA	ACTV	Illegal *2
	L	L	н	L	BA, AP	PRE/PALL	Precharge; Determine Precharge Type
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal

Current State	cs	RAS	CAS	WE	Addr	Command	Function Notes
Read	н	х	х	х	х	DESL	NOP (Continue Burst to End \rightarrow Bank Active)
	L	н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Bank Active)
	L	н	н	L	Х	BST	Burst Stop \rightarrow Bank Active
	L	н	L	Н	BA, CA, AP	READ/READA	Terminate Burst, New Read; Determine AP
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Terminate Burst, Start Write; *4 Determine AP
	L	L	н	Н	BA, RA	ACTV	Illegal *2
	L	L	Н	L	BA, AP	PRE/PALL	Terminate Burst, Precharge; \rightarrow Idle Determine Precharge Type
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal
Write	н	x	х	х	Х	DESL	NOP (Continue Burst to End \rightarrow Bank Active)
	L	н	Н	Н	Х	NOP	NOP (Continue Burst to End \rightarrow Bank Active)
	L	Н	н	L	Х	BST	Burst Stop \rightarrow Bank Active
	L	н	L	Н	BA, CA, AP	READ/READA	Terminate Burst, Start Read; Determine AP
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Terminate Burst, New Write; Determine AP
	L	L	Н	Н	BA, RA	ACTV	Illegal *2
	L	L	Н	L	BA, AP	PRE/PALL	Terminate Burst, Precharge; Determine Precharge Type
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal

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Current State	CS	RAS	CAS	WE	Addr	Command	Function Notes
Read with Auto- Precharge	Н	х	х	х	х	DESL	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)
Frecharge	L	н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)
	L	Н	Н	L	Х	BST	Illegal
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal
	L	L	Н	Н	BA, RA	ACTV	Illegal *2
	L	L	Н	L	BA, AP	PRE/PALL	Illegal *2
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal
Write with Auto- Precharge	Н	х	х	Х	х	DESL	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)
Frecharge	L	Н	Н	Н	х	NOP	NOP (Continue Burst to End \rightarrow Precharge \rightarrow Idle)
	L	н	н	L	Х	BST	Illegal
	L	н	L	Н	BA, CA, AP	READ/READA	Illegal
	L	н	L	L	BA, CA, AP	WRIT/WRITA	Illegal
	L	L	Н	Н	BA, RA	ACTV	Illegal *2
	L	L	Н	L	BA, AP	PRE/PALL	Illegal *2
	L	L	L	Н	Х	REF/SELF	Illegal
	L	L	L	L	MODE	MRS	Illegal

Current State	CS	RAS	CAS	WE	Addr	Command	Function	Notes
Precharge	Н	Х	Х	Х	Х	DESL	NOP (Idle after tRP)	
	L	Н	н н н		Х	NOP	NOP (Idle after t _{RP})	
	L	Н	н	L	Х	BST	Illegal	
	L	Н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	н	Н	BA, RA	ACTV	Illegal	*2
	L	L	н	L	BA, AP	PRE/PALL	NOP (PALL may effect other bank)	*5
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	
Bank Activating	Н	Х	Х	Х	Х	DESL	NOP (Bank Active after tRCD)	
Activating	L	Н	н	Н	Х	NOP	NOP (Bank Active after tRCD)	
	L	Н	Н	L	Х	BST	NOP (Bank Active after tRCD)	
	L	Н	L	Н	BA, CA, AP	READ/READA	Illegal	*2
	L	Н	L	L	BA, CA, AP	WRIT/WRITA	Illegal	*2
	L	L	н	Н	BA, RA	ACTV	Illegal	*2
	L	L	н	L	BA, AP	PRE/PALL	Illegal	*2
	L	L	L	Н	Х	REF/SELF	Illegal	
	L	L	L	L	MODE	MRS	Illegal	

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Current State	CS	RAS	CAS	WE	Addr	Command	Function Notes
Refreshing	Н	Х	Х	Х	Х	DESL	NOP (Idle after trc)
	L	Н	Н	Х	Х	NOP/BST	NOP (Idle after trc)
	L	н	L	Х	Х	READ/READA WRIT/WRITA	Illegal
	L	L	Н	Х	Х	ACTV/ PRE/PALL	Illegal
	L	L	L	Х	Х	REF/SELF MRS	Illegal
Mode Register	Н	Х	Х	Х	Х	DESL	NOP (Idle after Imrd)
Setting	L	Н	Н	Н	Х	NOP	NOP (Idle after Imrd)
	L	Н	Н	L	Х	BST	Illegal
	L	н	L	Х	х	READ/READA/ WRIT/WRITA	Illegal
	L	L	х	Х	Х	ACTV/PRE/ PALL/REF/ SELF/MRS	Illegal

ABBREVIATIONS:

RA = Row Address	BA = Bank Address
CA = Column Address	AP = Auto Precharge

COMMAND TRUTH TABLE FOR CKE

Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes
Self- refresh	Н	Х	Х	Х	Х	Х	Х	Invalid
renean	L	Н	Н	Х	Х	Х	х	Exit Self-refresh (Self-refresh Recovery \rightarrow Idle after t _{RC})
	L	Н	L	Н	Н	Н	Х	Exit Self-refresh (Self-refresh Recovery \rightarrow Idle after tRC)
	L	Н	L	Н	Н	L	Х	Illegal
	L	Н	L	Н	L	Х	Х	Illegal
	L	Н	L	L	Х	Х	Х	Illegal
	L	L	Х	Х	Х	Х	Х	NOP (Maintain Self-refresh)
Self- refresh	L	Х	Х	Х	Х	Х	Х	Invalid
Recovery	Н	Н	Н	Х	Х	Х	Х	Idel after tRC
	Н	Н	L	Н	Н	Н	Х	Idel after tRC
	Н	Н	L	Н	Н	L	Х	Illegal
	Н	Н	L	Н	L	Х	Х	Illegal
	Н	Н	L	L	Х	Х	Х	Illegal
	Н	L	Х	Х	Х	Х	Х	Illegal

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Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes	
Power Down	н	Х	Х	Х	Х	Х		Invalid	
Down	L	Н	Н	Х	Х	Х	Х	Exit Power Down Mode \rightarrow Idle	
	L	п	L	Н	Н	Н	Х		
	L	L	Х	Х	Х	Х	Х	NOP (Maintain Power Down Mode)	
	L	Н	L	L	Х	Х	Х	Illegal	
	L	Н	L	Н	L	Х	Х	Illegal	
Both Banks	Н	Н	Н	Х	Х	Х		Refer to the Operation Command Table.	
Idle	Н	Н	L	Н	Х	Х		Refer to the Operation Command Table	
	Н	Н	L	L	Н	Х		Refer to the Operation Command Table	
	Н	Н	L	L	L	Н	Х	Auto-refresh	
	Н	Н	L	L	L	L	MODE	Refer to the Operation Command Table.	
	Н	L	Н	Х	Х	Х	Х	Power Down	
	Н	L	L	Н	Н	Н	Х	Power Down	
	Н	L	L	Н	Н	L	Х	Illegal	
	Н	L	L	Н	L	Х		Illegal	
	Н	L	L	L	Н	Х		Illegal	
	н	L	L	L	L	Н	Х	Self-refresh	
	Н	L	L	L	L	L	SPECIAL MODE	Refer to the Operation Command Table.	
	Н	L	L	L	L	L	MODE	Refer to the Operation Command Table.	
	L	Х	Х	Х	Х	Х	Х	Invalid	

(Continued)

Current State	CKE n-1	CKE n	CS	RAS	CAS	WE	Addr	Function Notes		
Bank Active Bank	Н	Н	Х	Х	Х	Х	Х	Refer to the Operation Command Table.		
Activating Read/Write	Н	L	Х	Х	Х	Х	Х	Begin Clock Suspend Next Cycle		
	L	Н	Х	Х	Х	Х	Х	Exit Clock Suspend Next Cycle		
	L	L	Х	Х	Х	Х	Х	Maintain Clock Suspend		
Clock	Н	Х	Х	Х	Х	Х	Х	Invalid		
Suspend	L	Н	Х	Х	Х	Х	Х	Exit Clock Suspend Next Cycle		
	L	L	Х	Х	Х	Х	Х	Maintain Clock Suspend		
Any State Other Than	L	Х	Х	Х	Х	Х	Х	Invalid		
Listed	Н	Н	Х	Х	Х	Х	Х	Refer to the Operation Command Table		
1.5010	Н	L	Х	Х	Х	Х	Х	Begin Clock Suspend Next Cycle		

Notes: 1. All entries assume the CKE was High during the proceeding clock cycle and the current clock cycle.

2. Illegal to bank in specified state; entry may be legal in the bank specified by BA, depending on the state of that bank.

- 3. Illegal if any bank is not idle.
- 4. Must satisfy bus contention, bus turn around, and/or write recovery requirements.
- 5. NOP to bank precharging or in idle state. May precharge bank spesified by BA (and AP).
- 6. SELF command should only be issued after the last read data have been appeared on DQ.
- 7. MRS command should only be issued on condition that all DQ are in Hi-Z.

■ FUNCTIONAL DESCRIPTION

SDRAM BASIC FUNCTION

Three major differences between this SDRAM and conventional DRAMs are: synchronized operation, burst mode, and mode register.

The **synchronized operation** is the fundamental difference. An SDRAM uses a clock input for the synchronization, where the DRAM is basically asynchronous memory although it has been using two clocks, RAS and CAS. Each operation of DRAM is determined by their timing phase difference while each operation of SDRAM is determined by commands and all operations are referenced to a positive clock edge. Fig 3 show the basic timing diagram differences between SDRAMs and DRAMs.

The **burst mode** is a very high speed access mode utilizing an internal column address generator. Once a column addresses for the first access is set, following addresses are automatically generated by the internal column address counter.

The **mode register** is to justify the SDRAM operation and function into desired system conditions. MODE REGISTER TABLE shows how SDRAM can be configured for system requirement by mode register programming.

CLOCK (CLK) and CLOCK ENABLE (CKE)

All input and output signals of SDRAM use register type buffers. A CLK is used as a trigger for the register and internal burst counter increment. All inputs are latched by a positive edge of CLK. All outputs are validated by the CLK. CKE is a high active clock enable signal. When CKE = Low is latched at a clock input during active cycle, the next clock will be internally masked. During idle state (all banks have been precharged), the power Down mode (standby) is entered with CKE = Low and this will make extremely low standby current.

CHIP SELECT (CS)

 \overline{CS} enables all commands inputs, \overline{RAS} , \overline{CAS} , and \overline{WE} , and address input. When \overline{CS} is High, command signals are negated but internal operation such as burst cycle will not be suspended. If such a control isn't needed, \overline{CS} can be tied to ground level.

COMMAND INPUT (RAS, CAS and WE)

Unlike a conventional DRAM, RAS, CAS, and WE do not directly imply SDRAM operation, such as Row address strobe by RAS. Instead, each combination of RAS, CAS, and WE input in conjunction with CS input at a rising edge of the CLK determines SDRAM operation. Refer to FUNCTION TRUTH TABLE in page 5.

ADDRESS INPUT (Ao to A10)

Address input selects an arbitrary location of a total of 524,288 words of each memory cell matrix. A total of nineteen address input signals are required to decode such a matrix. SDRAM adopts an address multiplexer in order to reduce the pin count of the address line. At a Bank Active command (ACTV), eleven Row addresses are initially latched and the remainder of eight Column addresses are then latched by a Column address strobe command of either a Read command (READ or READA) or Write command (WRIT or WRITA).

BANK SELECT (A11)

This SDRAM has two banks and each bank is organized as 512K words by 16-bit.

Bank selection by A₁₁ occurs at Bank Active command (ACTV) followed by read (READ or READA), write (WRIT or WRITA), and precharge command (PRE).

DATA INPUT AND OUTPUT (DQ₀ to DQ₁₅)

Input data is latched and written into memory at the clock following the write command input. Data output is obtained by the following conditions followed by a read command input:

tRAC ; from the bank active command when tRCD (min) is satisfied. (This parameter is reference only.)

tcac ; from the read command when tRCD is greater than tRCD (min).

tac ; from the clock edge after tRAC and tCAC.

The polarity of the output data is identical to that of the input. Data is valid between access time (determined by the three conditions above) and the next positive clock edge (toh).

DATA I/O MASK (DQML/DQMU)

DQML and DQMU are active high enable inputs and have an output disable and input mask function. During burst cycle and when DQML/DQMU = High is latched by a clock, input is masked at the same clock and output will be masked at the second clock later while internal burst counter will increment by one or will go to the next stage depending on burst type.

DQML controls lower byte (DQ₀ to DQ₇) and DQMU (DQ₈ to DQ₁₅) controls upper byte.

BURST MODE OPERATION AND BURST TYPE

The burst mode provides faster memory access. The burst mode is implemented by keeping the same Row address and by automatic strobing column address. Access time and cycle time of Burst mode is specified as t_{AC} and t_{CK}, respectively. The internal column address counter operation is determined by a mode register which defines burst type and burst count length of 1,2, 4 or 8 bits of boundary. In order to terminate or to move from the current burst mode to the next stage while the remaining burst count is more than 1, the following combinations will be required:

Current Stage	Next Stage	N	Method (Assert the following command)				
Burst Read	Burst Read	Read Comma	ind				
Puret Bood	Irst Read Burst Write 1		Mask Command (Normally 3 clock cycles)				
Buist Reau			Write Command after Iowd				
Burst Write	Burst Write	Write Comma	ind				
Burst Write	Burst Read	Read Comma	ind				
Burst Read	Precharge	Precharge Co	ommand				
Burst Write	Precharge	Precharge Co	Precharge Command				

The burst type can be selected either sequential or interleave mode if burst length is 2, 4 or 8. The sequential mode is an incremental decoding scheme within a boundary address to be determined by count length, it assigns+1 to the previous (or initial) address until reaching the end of boundary address and then wraps round to least significant address(= 0). The interleave mode is a scrambled decoding scheme for A_0 and A_2 . If the first access of column address is even (0), the next address will be odd (1), or vice-versa.

BURST MODE OPERATION AND BURST TYPE (Continued)

When the full burst operation is executed at single write mode, Auto-precharge command is valid only at write operation.

The burst type can be selected either sequential or interleave mode. But only the sequential mode is usable to the full column burst.

The sequential mode is an incremental decoding scheme within a boundary address to be determined by burst length, it assigns+1 to the previous (or initial) address until reaching the end of boundary address and then wraps round to least significant address(=0).

Burst Length	Starting Column Address A ₂ A ₁ A ₀	Sequential Mode	Interleave
2	X X 0	0 – 1	0 – 1
2	X X 1	1 – 0	1 – 0
	X 0 0	0-1-2-3	0-1-2-3
4	X 0 1	1 - 2 - 3 - 0	1-0-3-2
4	X 1 0	2-3-0-1	2-3-0-1
	X 1 1	3-0-1-2	3-2-1-0
	0 0 0	0 - 1 - 2 - 3 - 4 - 5 - 6 - 7	0 - 1 - 2 - 3 - 4 - 5 - 6 - 7
	0 0 1	1 - 2 - 3 - 4 - 5 - 6 - 7 - 0	1 - 0 - 3 - 2 - 5 - 4 - 7 - 6
	0 1 0	2 - 3 - 4 - 5 - 6 - 7 - 0 - 1	2 - 3 - 0 - 1 - 6 - 7 - 4 - 5
8	0 1 1	3 - 4 - 5 - 6 - 7 - 0 - 1 - 2	3 - 2 - 1 - 0 - 7 - 6 - 5 - 4
0	1 0 0	4-5-6-7-0-1-2-3	4-5-6-7-0-1-2-3
	1 0 1	5 - 6 - 7 - 0 - 1 - 2 - 3 - 4	5-4-7-6-1-0-3-2
	1 1 0	6-7-0-1-2-3-4-5	6-7-4-5-2-3-0-1
	1 1 1	7 - 0 - 1 - 2 - 3 - 4 - 5 - 6	7-6-5-4-3-2-1-0

FULL COLUMN BURST AND BURST STOP COMMAND (BST)

The full column burst is an option of burst length and available only at sequential mode of burst type. This full column burst mode is repeatedly access to the same column. If burst mode reaches end of column address, then it wraps round to first column address (=0) and continues to count until interrupted by the news read (READ)/write (WRIT/ BWRIT), precharge (PRE), or burst stop (BST) command. The selection of auto-precharge option is illegal during the full column burst operation except write command at BURST READ & SINGLE WRITE mode.

The BST command is applicable to terminated the burst operation. If the BST command is asserted during the burst mode, its operation is terminated immediately and the internal state moves to Bank Active.

When read mode is interrupted by BST command, the output will be in High-Z.

For the detail rule, please refer to Timing Diagram-8.

When write mode is interrupted by BST command, the data to be applied at the same time with BST command will be ignored.

BURST READ & SINGLE WRITE

The burst read and single write mode provides single word write operation regardless of its burst length. In this mode, burst read operation does not be affected by this mode.

PRECHARGE AND PRECHARGE OPTION (PRE, PALL)

SDRAM memory core is the same as conventional DRAMs', requiring precharge and refresh operations. Precharge rewrites the bit line and to reset the internal Row address line and is executed by the Precharge command (PRE). With the Precharge command, SDRAM will automatically be in standby state after precharge time (trp).

The precharged bank is selected by combination of AP and A_{11} when Precharge command is asserted. If AP = High, both banks are precharged regardless of A_{11} (PALL). If AP = Low, a bank to be selected by A_{11} is precharged (PRE).

The auto-precharge enters precharge mode at the end of burst mode of read or write without Precharge command assertion.

This auto precharge is entered by AP = High when a read or write command is asserted. Refer to FUNCTION TABLE.

AUTO-REFRESH (REF)

Auto-refresh uses the internal refresh address counter. The SDRAM Auto-refresh command (REF) generates Precharge command internally. All banks of SDRAM should be precharged prior to the Auto-refresh command. The Auto-refresh command should also be asserted every 16 μ s or a total 2,048 refresh commands within a 32.8 ms period.

SELF-REFRESH ENTRY (SELF)

Self-refresh function provides automatic refresh by an internal timer as well as Auto-refresh and will continue the refresh function until cancelled by SELFX.

The Self-refresh is entered by applying an Auto-refresh command in conjunction with CKE = Low (SELF). Once SDRAM enters the self-refresh mode, all inputs except for CKE will be "don't care" (either logic high or low level state) and outputs will be in a High-Z state. During a self-refresh mode, CKE = Low should be maintained. SELF Command should only be issued after last read data has been appeared on DQ.

SELF-REFRESH EXIT (SELFX)

To exit self-refresh mode, apply minimum tPDE after CKE brought high, and then the NOP command (NOP) or the Deselect command (DESL) should be asserted within one tRc period. CKE should be held High within one tRc period after tPDE. Refer to Timing Diagram for the detail.

It is recommended to assert an Auto-refresh command just after the tRC period to avoid the violation of refresh period.

MODE REGISTER SET (MRS)

The mode register of SDRAM provides a variety of different operations. The register consists of four operation fields; Burst Length, Burst Type, CAS latency, and Operation Code. Refer to MODE REGISTER TABLE in page 31.

The mode register can be programmed by the Mode Register Set command (MRS). Each field is set by the address line. Once a mode register is programmed, the contents of the register will be held until re-programmed by another MRS command (or part loses power). MRS command should only be issued on condition that all DQ is in Hi-Z.

The condition of the mode register is undefined after the power-up stage. It is required to set each field after initialization of SDRAM.

Refer to POWER-UP INITIALIZATION below.

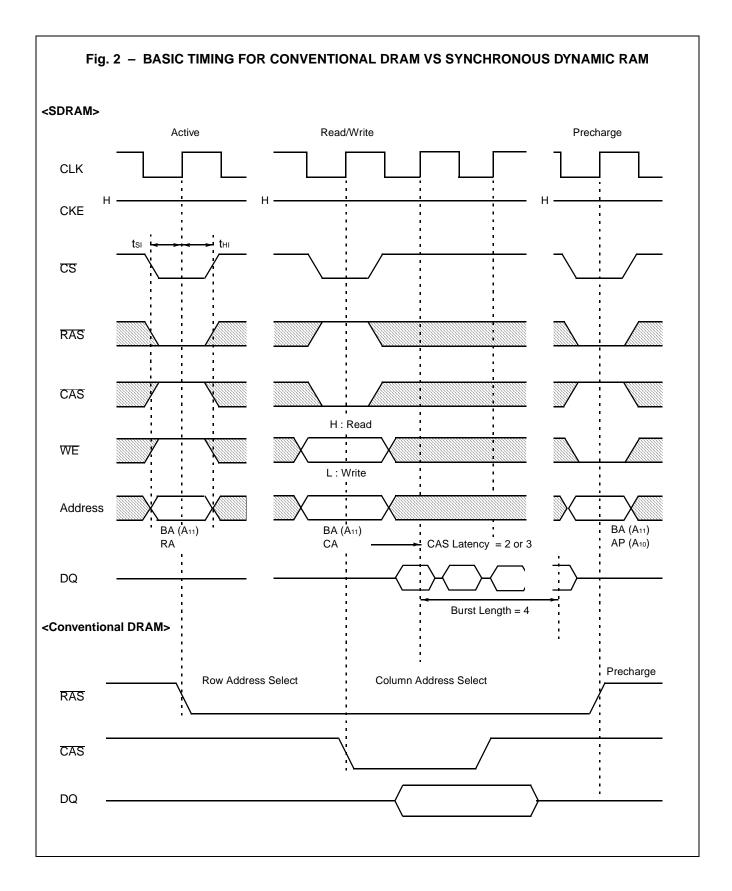
POWER-UP INITIALIZATION

The SDRAM internal condition after power-up will be undefined. It is required to follow the following Power On Sequence to execute read or write operation.

- 1. Apply power and start clock. Attempt to maintain either NOP or DESL command at the input.
- 2. Maintain stable power, stable clock, and NOP condition for a minimum of 200 µs.
- 3. Precharge all banks by Precharge (PRE) or Precharge All command (PALL).
- 4. Assert minimum of 8 Auto-refresh command (REF).
- 5. Program the mode register by Mode Register Set command (MRS).

In addition, it is recommended DQM and CKE to track Vcc to insure that output is High-Z state. The mode register set command (MRS) can be set before 8 Auto-refresh command (REF).

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MINIMUM CLOCK LATENCY OR DELAY TIME FOR 1 BANK OPERATION

Second command (opposite bank) First command	MRS	ACTV	READ	READA	WRIT	WRITA	PRE	PALL	REF	SELF
MRS	Imrd	Imrd							Imrd	Imrd
ACTV			t RCD	trcd	trcd	trcd	tras	tras		
READ			1	1	*1 1	*1 1	1	1		
READA	BL + t _{RP}	BL + t _{RP}							BL + t _{RP}	BL + t _{RP}
WRIT			twr	twr	1	1	trwL	trwL		
WRITA	BL + trwL + trp	BL + trwL + trp							BL + trwL + trp	BL + trwL + trp
PRE	*3 t RP	*3 t RP							*3 t RP	*3 trp
PALL	*3 t RP	*3 t RP							*3 t RP	*3 t RP
REF	trc	trc							trc	t RC
SELF	tpde + trc	tpde + trc							tpde + trc	tpde + trc

Notes: *1. Assume no I/O conflict.

*2. If $t_{\text{RP}} \leq t_{\text{CK}},$ minimum latency is a sum of BL + CL.

*3. Assume output is in High-Z state.

Illegal Command

MINIMUM CLOCK LATENCY OR DELAY TIME FOR 2 BANK OPERATION

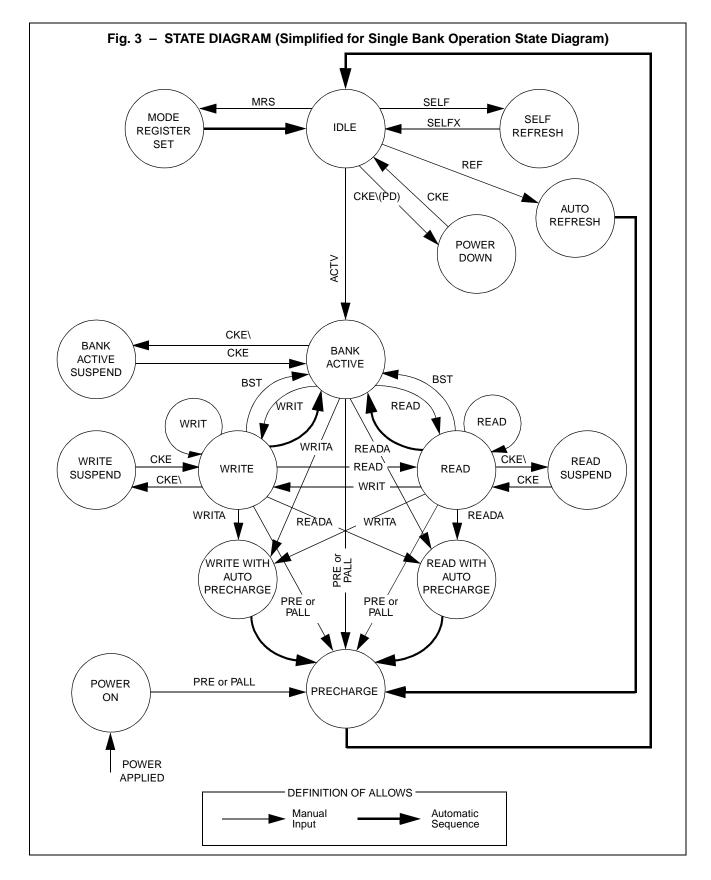
Second command (opposite bank) First command	MRS	ACTV	READ	READA	WRIT	WRITA	PRE	PALL	REF	SELF
MRS	Imrd	Imrd							Imrd	Imrd
ACTV		*1 t rrd	*2 1	*2 1	*2 1	*2 1	*7 1	tras		
READ		*1 1	*2 1	*2 1	*2 *3 1	*2 *3 1	*7 1	tras		
READA		*1 1					1		*1 *4 BL + t _{RP}	*1 *4 BL + t _{RP}
WRIT		*1 1	*2 1	*2 1	*2 1	*2 1	*7 1	tras		
WRITA		*1 1					1		*1 BL + 1 + t _{RP}	*1 BL + 1 + t _{RP}
PRE	*1 trp	*1 1	*2 1	*2 1	*2 1	*2 1	1	tras	*1 t RP	*1 trp
PALL *5	trp	*1 t RP					1	1	*1 *6 t RP	*1 *6 t RP
REF	t RC	trc							trc	t RC
SELF	trc	trc							trc	trc

Notes: *1. Assume opposite bank is in idle state.

*2. Assume opposite bank is in active state.

- *3. Assume no I/O conflict.
- *4. If $t_{RP} \leq t_{CK}$, minimum latency is a sum of BL + CL.
- *5. Assume PALL command dose not affect any operation on opposite bank.
- *6. Assume Output is in High-Z sate.
- *7. Assume tras of opposite bank is satisfied.

Illegal Command



■ ABSOLUTE MAXIMUM RATINGS (See WARNING)

Parameter	Symbol	Value	Unit
Voltage of Vcc Supply Relative to Vss	Vcc, Vccq	-0.5 to +4.6	V
Voltage at Any Pin Relative to Vss	Vin, Vout	-0.5 to +4.6	V
Short Circuit Output Current	Ιουτ	-50 to +50	mA
Power Dissipation	PD	1.3	W
Storage Temperature	Тѕтс	-55 to +125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

(Referenced to Vss)

Parameter	Notes	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage		Vcc, Vccq	3.0	3.3	3.6	V
Supply voltage		Vss, Vssq	0	0	0	V
Input High Voltage	*1	Vін	2.0	_	Vcc + 0.5	V
Input Low Voltage	*2	VIL	-0.5	_	0.8	V
Ambient Temperature		TA	0		70	°C

Notes: *1. Overshoot limit : VIH (max) = TBD.

*2. Undershoot limit : V_{IL} (min) = -1.5 V with a pulsewidth \leq 5 ns.

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses , operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

 $(T_A = 25^{\circ}C, f = 1 \text{ MHz})$

Parameter	Symbol	Тур.	Max.	Unit
Input Capacitance, Address		—	4	pF
Input Capacitance, Except for Address	CIN2		4	pF
I/O Capacitance	Cı/o		7	pF

■ DC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.) Notes 1, 2

Doro	motor	Symbol	Condition	Va	lue	Unit
Para	meter	Symbol	Condition	Min.	Max.	Unit
Output High Voltage		VOH(DC)	Іон = –2 mA	2.4	_	V
Output Low Voltage		Vol(DC)	IoL = 2 mA	_	0.4	V
Input Leakage Current (any input)		Ιu	$0 V \le V_{IN} \le V_{CC};$ All other pins not under test = 0 V	-10	10	μA
Output Leakage Curr	ent	Ilo	0 V ≤ V _{IN} ≤ V _{CC} ; Data out disabled	-10	10	μA
	MB811171622A-125		No Burst ;		90	
	MB811171622A-100	Icc1s	tск = min t _{RC} = min		85	mA
	MB811171622A-84	10015	One bank active	_	80	IIIA
Operating Current (Average Power	MB811171622A-67		$0 V \le V \le V cc$		75	
Supply Current)	MB811171622A-125		No Burst ;		140	
	MB811171622A-100	Icc1D	tск = min t _{RC} = min	_	130	— mA
	MB811171622A-84	ICCID	All banks active	_	120	
	MB811171622A-67		$0 V \le V$ IN $\le V$ CC		110	
Precharge Standby C		CC2P	$\begin{array}{l} CKE = V_{IL} \\ AII \text{ banks idle} \\ tck = min \\ Power down mode \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	2	mA
(Power Supply Curre	nt)	Icc2N	$\begin{array}{l} CKE = V_{IH} \\ All \ banks \ idle \\ tck = min \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	30	mA
Active Standby Curre	ent	Іссзр	$\begin{array}{l} CKE = V_{IL} \\ Any \ bank \ active \\ tck = min \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	30	mA
(Power Supply Current)		Іссзи	$\begin{array}{l} CKE = V_{IH} \\ Any \text{ bank active} \\ t_{CK} = \min \\ 0 \ V \leq V_{IN} \leq V_{CC} \end{array}$	_	50	mA
	MB811171622A-125				150	mA
Burst mode Current	MB811171622A-100	1.	tск = min	—	135	
(Average Power Supply Current)	MB811171622A-84	ICC4	$0 V \le V_{IN} \le V_{CC}$		125	
	MB811171622A-67	1		_	115	
	1	1	I		(Co	ntinuea

Boro	Parameter		Condition	Va	Unit	
		Symbol	Condition	Min.	Max.	
Refresh Current #1	MB811171622A-125		Auto rofroch i		120	
	MB811171622A-100		Auto-refresh ; tск = min		110	
(Average Power Supply Current)	MB811171622A-84		trc = min 0 V ≤ VıN ≤ Vcc		100	mA
	MB811171622A-67	-	$\mathbf{O} \mathbf{V} \leq \mathbf{V} \mathbf{N} \leq \mathbf{V} \mathbf{C} \mathbf{C}$		90	
Refresh Current #2 (Average Power Supply Current)		Icc6	$ Self-refresh ; \\ CKE = V_{IL} \\ 0 V \le V_{IN} \le V_{CC} $	_	2	mA

■ AC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.) Note 2, 3, 4

Paramete	r Notes	Symbol		171622A 25		171622A 00		171622A 84		171622A 67	Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Clock Period	CAS Latency = 2	tск	12		15		17		20		ns
CIUCK FEIIUU	CAS Latency = 3	ICK	8		10		12		15		ns
Clock High Tin	ne	tсн	3.5		4		4		4		ns
Clock Low Tim	ie	tc∟	3.5		4		4		4		ns
Input Setup Ti	me	tsi	3		3		3		3		ns
Input Hold Tim	Input Hold Time		1		1		1		1		ns
Acess Time from Clock	CAS Latency = 2	- tac		9		9		9		10	ns
(tск = min) *5, 6	CAS Latency = 3			7.5		8.5		8.5		9	ns
Output in Low-	Z *7	t∟z	2		3		3		3		ns
Output in High	-Z *7	tнz	2		3		3		3		ns
Output Hold Ti	me *7	tон	2		3		3		3		ns
Time between Refresh		t REF		32.8		32.8		32.8		32.8	ms
Transition Time		t⊤	0.5	2	0.5	2	0.5	2	0.5	2	ns
Power Down E	xit Time	t PDE	3	—	3	—	4	—	5	—	ns

BASE VALUES FOR CLOCK COUNT/LATENCY

Parameter	Notes	Symbol	MB811171622A -125		MB811171622A -100		MB811171622A -84		MB811171622A -67		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
RAS Cycle Time	*8	t _{RC}	75	_	90	_	100		110	—	ns
RAS Access Time	*9	t RAC	_	45	_	54	_	56	_	60	ns
CAS Access Time	*10,13	t CAC	_	21	_	24	_	26	_	30	ns
RAS Precharge Tim	е	t RP	27		30		35		40	_	ns
RAS Active Time		tras	48	100000	60	100000	65	100000	70	100000	ns
RAS to CAS Delay Time *11		t RCD	24		30		30		30		ns
Write Recovery Time		t wr	8		10		12		15	—	ns
Write to Precharge Delay Time		t RWL	8		10		12		15	_	ns
RAS to RAS Bank Active Delay Time		t rrd	24		30		30		30		ns

CLOCK COUNT FORMULA Note 13

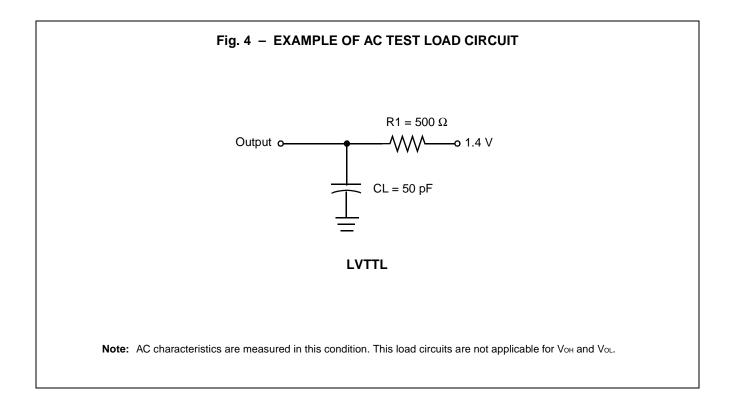
Base Value Clock Period (Round off a whole number) $Clock \ge -$

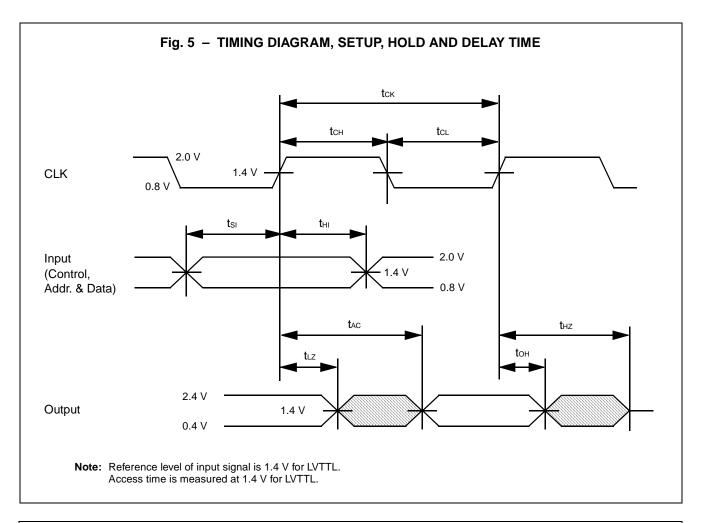
LATENCY - FIXED VALUES

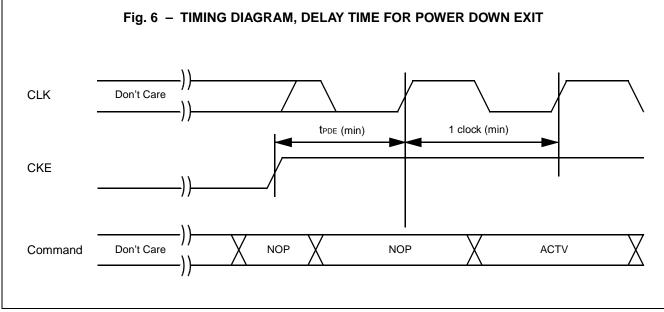
(The latency values on these parameters are fixed regardless of clock period.)

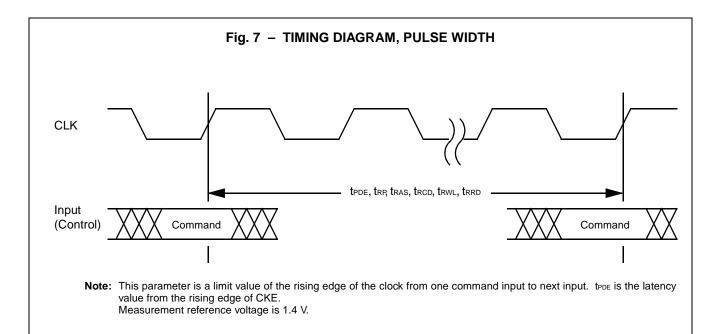
Parameter Notes		Symbol	MB811171622A -125	MB811171622A -100	MB811171622A -84	MB811171622A -67	Unit
CKE to Clock Disable		Іске	1	1	1	1	cycle
DQM to Output in High-Z		Idqz	2	2	2	2	cycle
DQM to Input Data Delay		DQD	0	0	0	0	cycle
Last Output to Write Command Delay		lowd	2	2	2	2	cycle
Write Command to Input Data Delay		lowd	0	0	0	0	cycle
Precharge to Output in High-Z Delay	CL = 2	- Ігон	2	2	2	2	cycle
	CL = 3		3	3	3	3	cycle
Burst Stop Command to Output in High-Z Delay	CL = 2	I=	2	2	2	2	cycle
	CL = 3	вѕн	3	3	3	3	cycle
Mode Register Access to Banks Active		Imrd	2	2	2	2	cycle
CAS to CAS Delay (min)		Ісср	1	1	1	1	cycle
CAS Bank Delay (min)		Ісвд	1	1	1	1	cycle

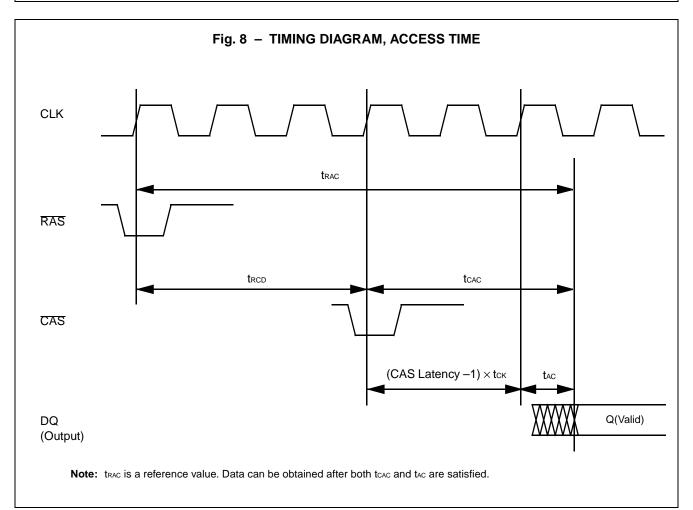
- **Notes:** *1. Icc depends on the output termination or load conditions, clock cycle rate, and signal clocking rate and address change; The specified values are obtained with the output open and no termination register and one time address change.
 - *2. An initial pause (DESL or NOP) of 200 μs is required after power-up followed by a minimum of eight Auto-refresh cycles.
 - *3. AC characteristics assume $t_T = 1$ ns and 50 pF of capacitive load.
 - *4. 1.4 V is the reference level for measuring timing of input signals. Transition times are measured between V_{H} (min) and V_{L} (max).
 - *5. Maximum value of CL = 2 depends on tcκ.
 - *6. tac also specifies the access time at burst mode except for first access.
 - *7. Specified where output buffer is no longer driven. toH, tLz and tHz define the time at which the output level achieves ±200 mV.
 - *8. Actual clock count of trc (Irc) will be sum of clock count of tras (Iras) and trp (Irp).
 - *9. trac is a reference value. Maximum value is obtained from the sum of trcd (min) and tcac (max).
 - *10. tcac is a reference value.
 - *11. Operation within the trcd (min) ensures that trac can be met; if trcd is greater than the specified trcd (min), access time is determined by trac or tac.
 - *12. All base values are measured from the clock edge at the command input to the clock edge for the next command input. All clock counts are calculated by a simple formula: clock count equals base value divided by clock period (round off to a whole number).
 - *13. The tcac depend on the CAS Latency.





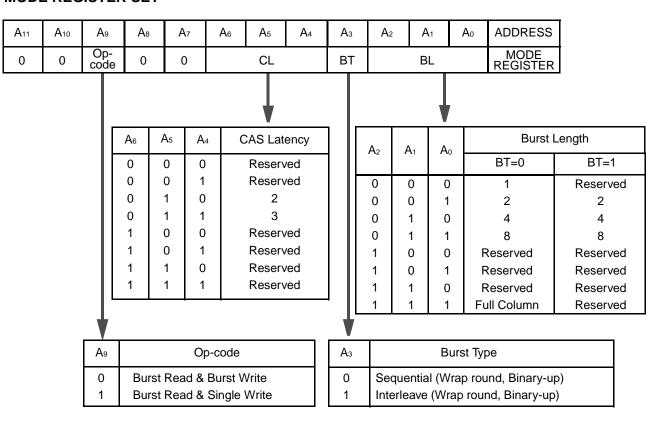




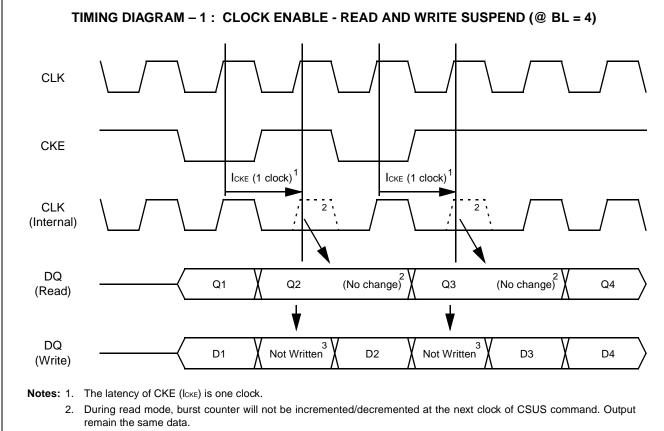


MODE REGISTER TABLE

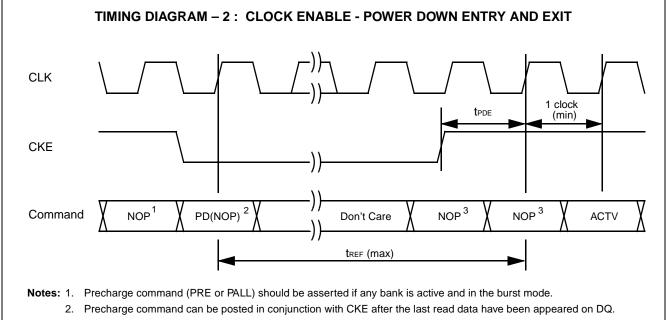
MODE REGISTER SET



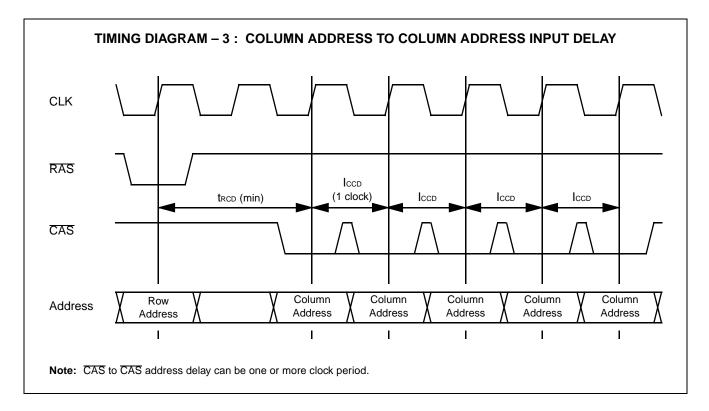
Note: When $A_9 = 1$, burst length at Write is always one regardless of BL value.

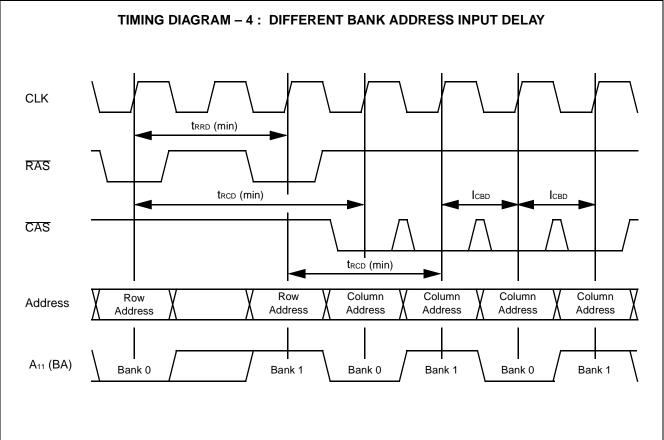


3. During the write mode, data at the next clock of CSUS command is ignored.

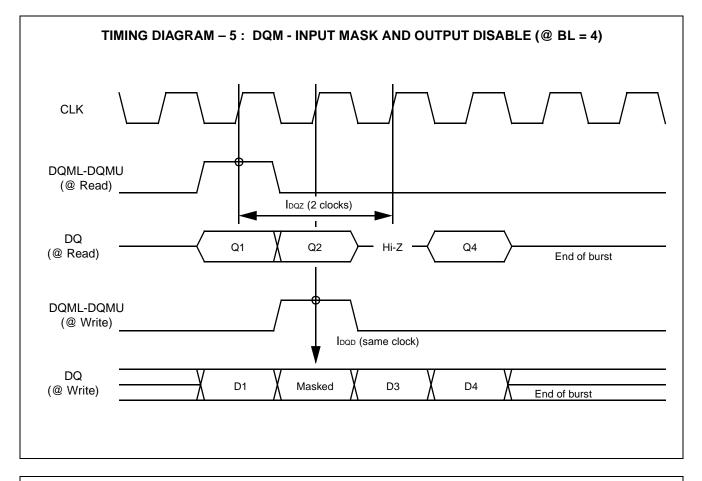


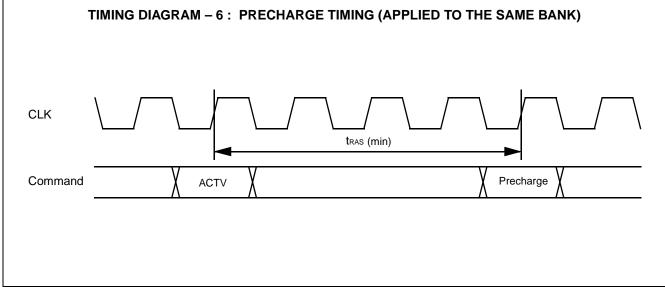
3. The ACTV command can be latched after tPDE (min) + 1 clock (min). It is recommended to apply NOP command in conjunction with CKE.

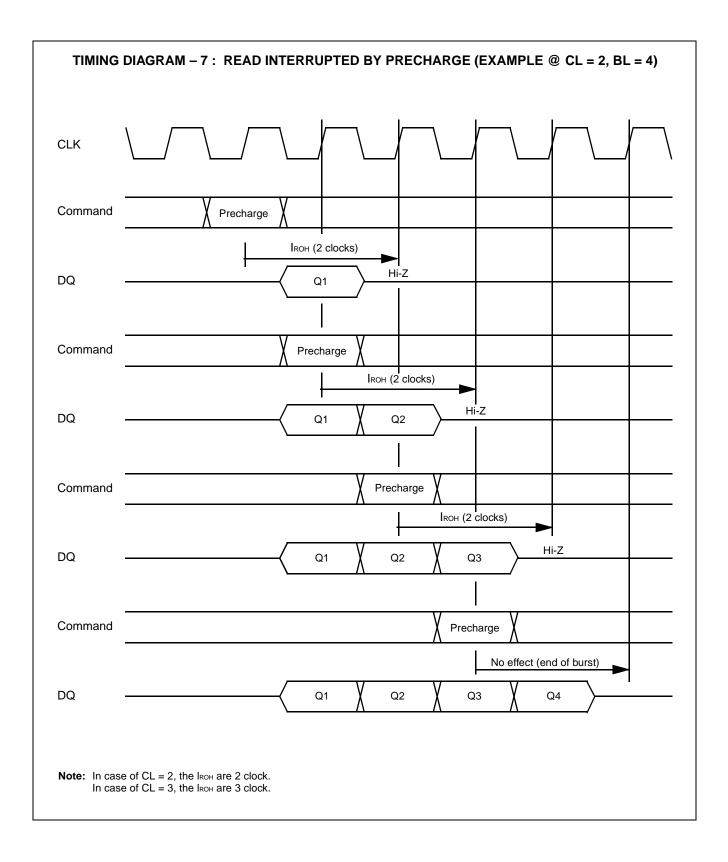


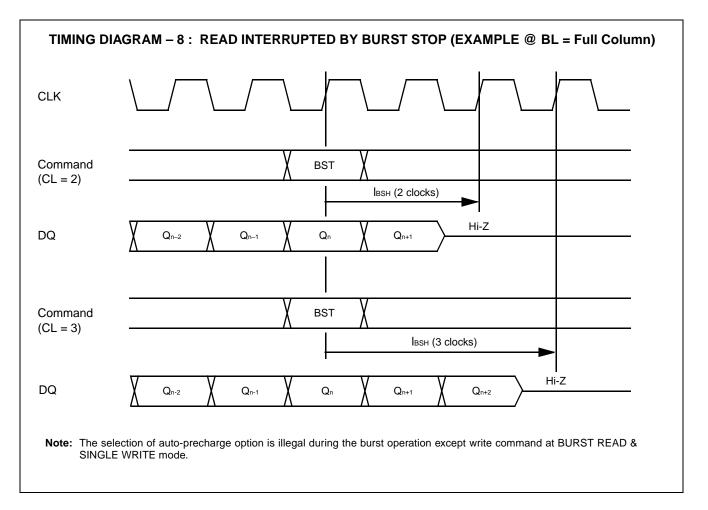


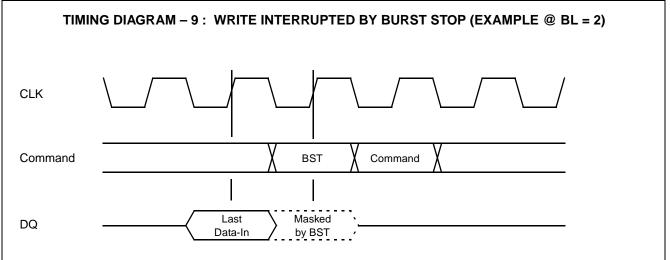
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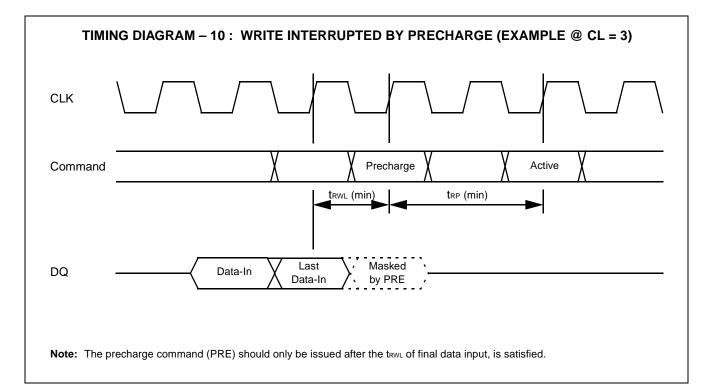


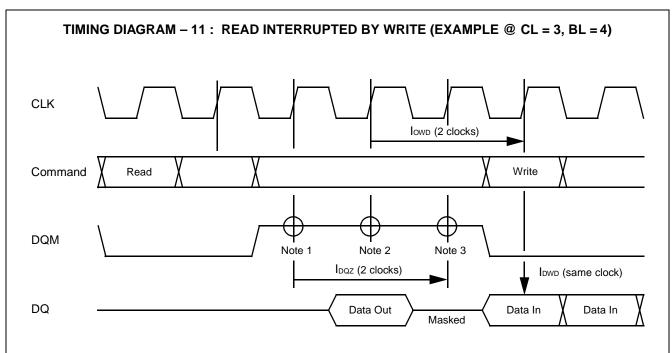








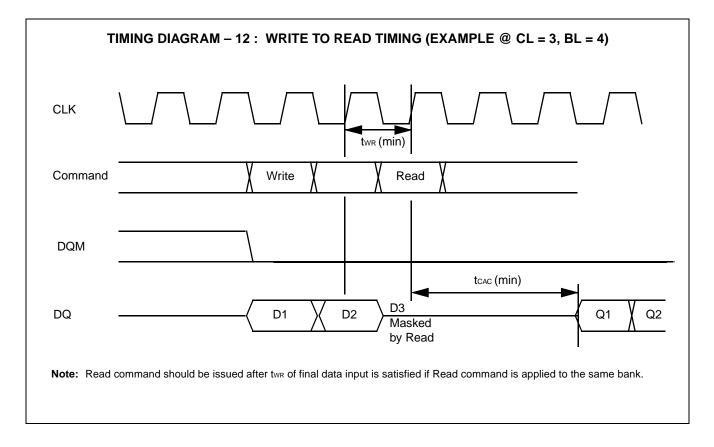


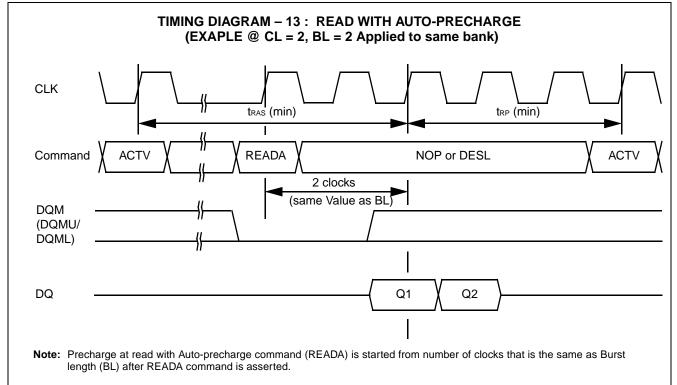


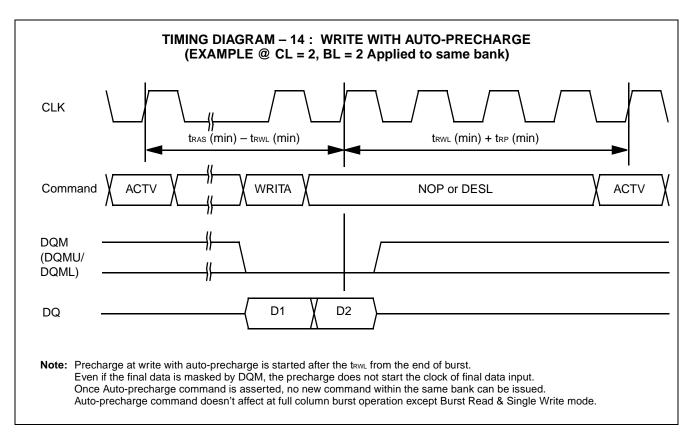
Notes: First DQM makes high impedance state High-Z between last output and first input data.

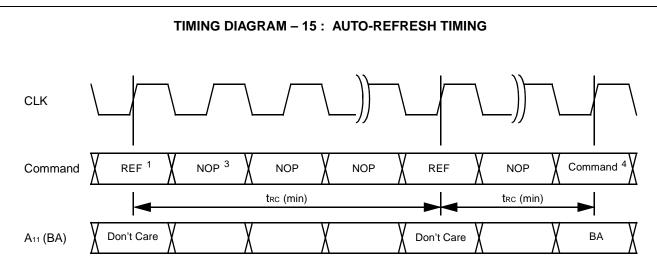
- 2. Second DQM makes internal output data mask to avoid bus contention.
- 3. Third DQM in illustrated above also makes internal output data mask. If burst read ends (final data output) at or after the second clock of burst write, this third DQM is required to avoid internal bus contention.

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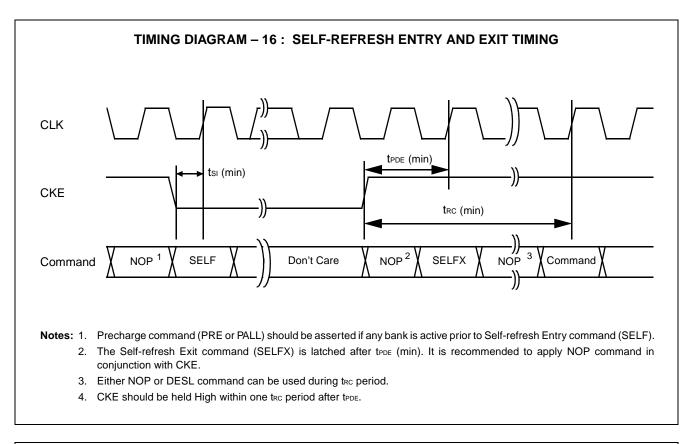


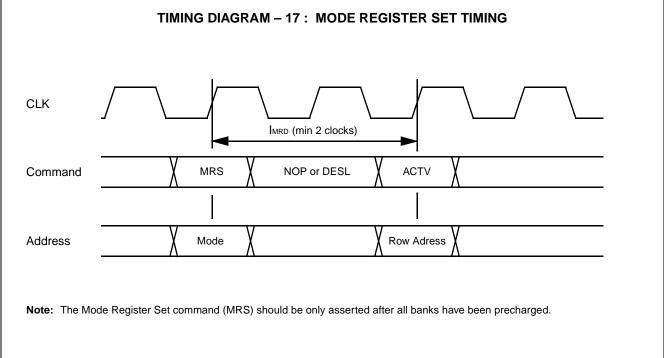


Notes: 1. All banks should be precharged prior to the first Auto-refresh command (REF).

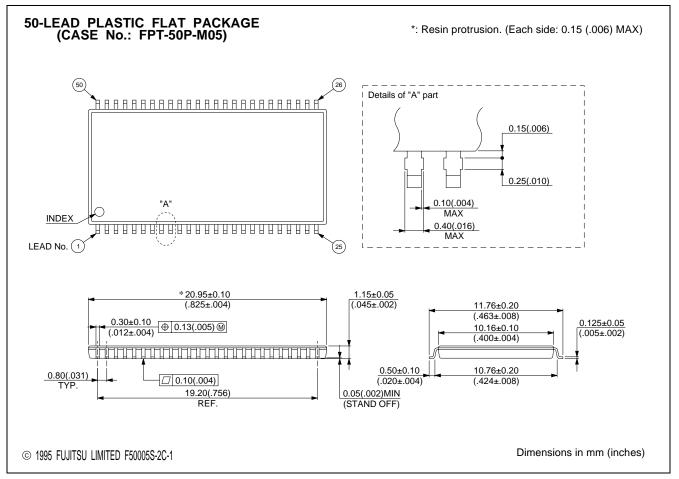
- 2. Bank select is ignored at REF command. The refresh address is selected by internal refresh counter, and both banks are internally selected simultaneously.
- 3. Either NOP or DESL command should be asserted during trc period while auto-refresh mode.
- 4. The activation command such as ACTV or MRS command other than REF command should be asserted after t_{RC} from the last REF command.

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PACKAGE DIMENSIONS



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